

## THERM-A-GAP G574

*Highly Conformable and Thermally Conductive Elastomer for Gap Filling Applications*

### DESCRIPTION

THERM-A-GAP elastomers are used to fill air gaps between PC boards or other components and heat sinks, metal enclosures, and chassis. The exceptional conformability of these advanced materials enables them to blanket highly uneven surfaces, transferring heat away from individual components or entire boards, and allowing chassis parts to be used as heat spreaders where space is restricted. The 574 thermal interface pads provide superior thermal performance and are softer than other THERM-A-GAP materials. G574 material consists of an extremely soft silicone elastomer loaded with ceramic particles, coated onto a fiberglass carrier. The “G” designates the fiberglass carrier that is on one side of the material. This reinforces the pad and makes one side of the pad non-tacky. The non-tacky side can be easily removed for component repairs. The flexible, elastic nature allows the material to blanket highly uneven surfaces, drawing away and transferring heat from components such as microprocessors, video chips, and power devices. These fiberglass-reinforced pads consist of an electrically non-conductive, ceramic filled silicone elastomer with a thermal conductivity of 1.6 W/m-K. These pads are best suited for applications where a gap of approximately 0.040 to 0.200 inch needs to be filled under pressures of 5 to 20 psi; other THERM-A-GAP™ products are available which may be more appropriate for different application conditions.

### APPLICATION

G574 is inherently self-adhering on the side opposite from the fiberglass carrier for ease of pad application. Remove the liner and place pad on the desired heat pipe or a microprocessor heat sink. The pads can be removed from the fiberglass side (non-tacky side) for rework. NOTE: Alternate application processes can be accommodated, please contact Chomerics Applications Engineering at 781-935-4850 for assistance with applications equipment and processes.

Typical Properties	G574	Test Method
Color	Light Gray	Visual
Carrier	Fiberglass	---
Thickness, inch (mm)	0.040 (1.0) to 0.200 (5.1)	ASTM D374
Thermal Impedance, @ 50°C, 10 psi, °C-in <sup>2</sup> /W	1.1 @ 0.040 inch to 2.8 @ 0.200 inch	ASTM D5470
Thermal Conductivity, @ 10 psi, W/m-K	1.6	ASTM D5470
Specific Gravity	1.7	ASTM D792
Hardness (Shore A)	<5	ASTM D2240

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